



DUAL P-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- ESD Protected Gate to 1kV
- Low Input Capacitance
- Fast Switching Speed
- Lead Free By Design/RoHS Compliant (Note 2)
- "Green" Device (Note 3)
- Qualified to AEC-Q 101 Standards for High Reliability

Mechanical Data

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.006 grams (approximate)

SOT-563





TOP VIEW Internal Schematic

Maximum Ratings @T_A = 25°C unless otherwise specified

Characte	ristic	Symbol	Value	Units	
Drain-Source Voltage		V _{DSS}	-50	V	
Gate-Source Voltage	Continuous	V_{GSS}	±8	V	
Drain Current (Note 2)	Continuous	I _D	-160	mA	

Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 1)	P _D	400	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ heta JA}$	313	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

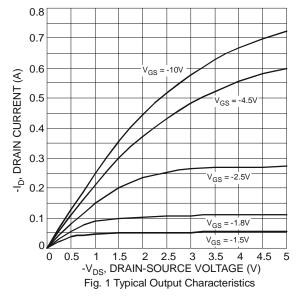
Electrical Characteristics @T_A = 25°C unless otherwise specified

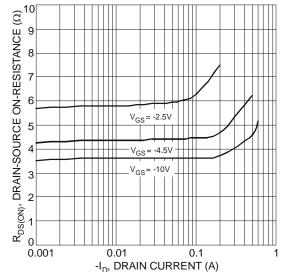
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)						
Drain-Source Breakdown Voltage	BV _{DSS}	-50	_	_	V	$V_{GS} = 0V$, $I_D = -250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-10	μА	$V_{DS} = -50V, V_{GS} = 0V$
Gate-Body Leakage	I _{GSS}	_	_	±500	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 4)						
Gate Threshold Voltage	$V_{GS(th)}$	-0.7	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance	D	_	4.6	6	()	$V_{GS} = -4V, I_{D} = -100mA$
Static Dialif-Source Off-Resistance	R _{DS} (ON)	_	6.0	8		$V_{GS} = -2.5V, I_D = -80mA$
Forward Transfer Admittance	Y _{fs}	100	_	_	mS	$V_{DS} = -5V, I_D = -100mA$
Diode Forward Voltage	V_{SD}	_	_	-1.2	V	$V_{GS} = 0V, I_{S} = -100mA$
DYNAMIC CHARACTERISTICS						
Input Capacitance	Ciss	_	29	_	рF	
Output Capacitance	Coss	_	7.3	_	pF	$V_{DS} = -25V$, $V_{GS} = 0V$, $f = 1.0MHz$
Reverse Transfer Capacitance	Crss	_	2.5	_	pF	

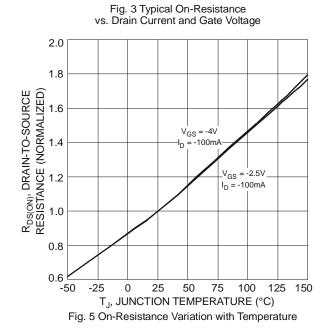
Notes:

- 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- No purposefully added lead.
- Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- 4. Short duration pulse test used to minimize self-heating effect.









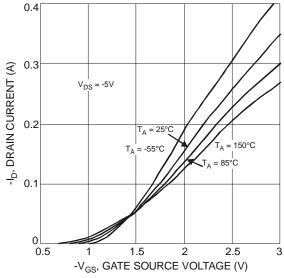


Fig. 2 Typical Transfer Characteristics

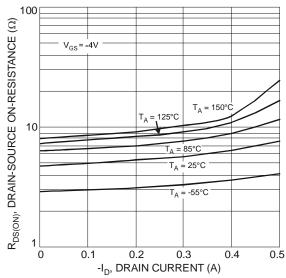
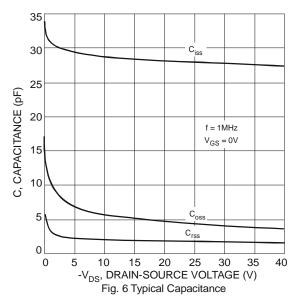
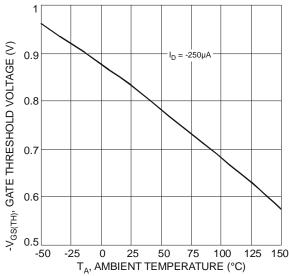


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature









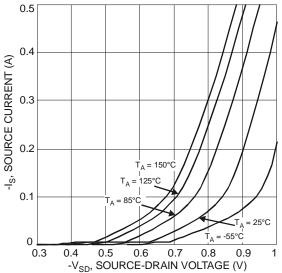


Fig. 8 Diode Forward Voltage vs. Current

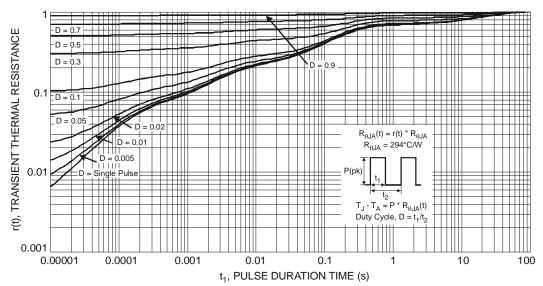


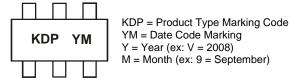
Fig. 9 Transient Thermal Response

Ordering Information (Note 5)

Part Number	Case	Packaging		
DMP57D5UV -7	SOT-563	3000/Tape & Reel		

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information (Note 6)



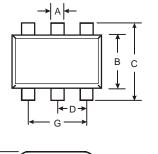
Notes: 6. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).

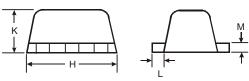
Date Code Key

Year	2008		2009	2010)	2011	2012	!	2013	2014		2015
Code	V		W	Х		Υ	Z		Α	В		С
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



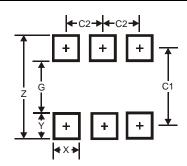
Package Outline Dimensions





SOT-563					
Dim	Min	Max	Тур		
A	0.15	0.30	0.20		
В	1.10	1.25	1.20		
C	1.55	1.70	1.60		
D	-	-	0.50		
G	0.90	1.10	1.00		
Η	1.50	1.70	1.60		
K	0.55	0.60	0.60		
L	0.10	0.30	0.20		
М	0.10	0.18	0.11		
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
С	1.7
F	0.5



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